

Welcome to **E-XFL.COM**

Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	32
Number of Macrocells	128
Number of Gates	6000
Number of I/O	64
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	84-LCC (J-Lead)
Supplier Device Package	84-PLCC (29.31x29.31)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/isplsi-1032e-100ljn

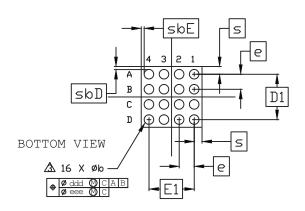
Email: info@E-XFL.COM

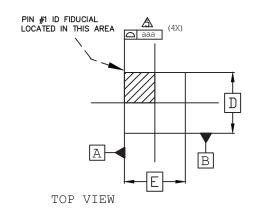
Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

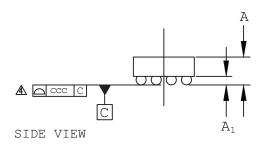


16-Ball WLCS Package Option 2: iCE40 UltraLite™

Dimensions in Millimeters







NOTES:

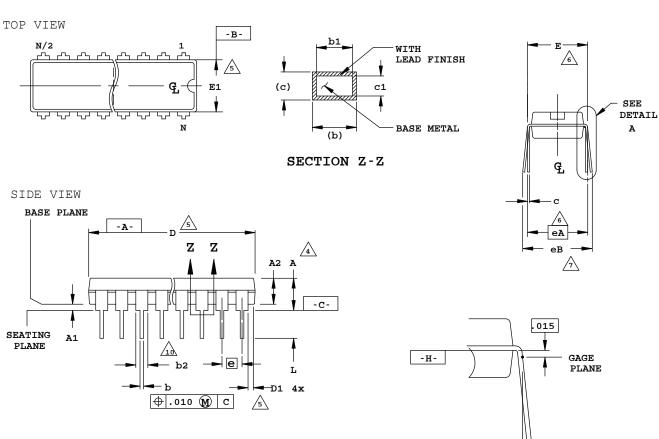
- 1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- A PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- $\underline{\mathbb{A}}$ BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

REF.	Min.	Nom.	Max.
Α	0.413	0.452	0.491
A1	0.122	0.152	0.182
b	0.188	0.218	0.248
D	1.	409 BS	С
Ε	1.	409 BS	С
D1		1.05 BSC)
E1		1.05 BSC)
е	(0.35 BS0)
S	-	0.180	-
sbD	0.067	0.071	0.072
sbE	0.067	0.071	0.072
۵۵۵	0.03		
CCC	0.03		
ddd	0.050		
eee		0.015	



24-Pin Plastic DIP

Dimensions in Inches



NOTES:

- 1. CONTROLLING DIMENSION: INCH.
- 2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M
- 3. DISTANCE BETWEEN LEADS INCLUDING DAMBAR
- PROTRUSIONS TO BE .005 MINIMUM. 4 DIMENSIONS A, A1 & L ARE MEASURED WITH
- THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
- DIMENSIONS D, D1 AND E1
 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
 MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010
- 6 E AND eA MEASURED WITH THE LEADS CONSTRAINED
- TO BE PERPENDICULAR TO DATUM -CPROPERTY OF THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
- 8 N IS THE MAXIMUM NUMBER OF LEAD
- POSITIONS. 9. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED
- TO EASE INSERTION
- 10 b2 MAXIMUM DIMENSIONS DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010
- 11. DATUM PLANE -H- COINCIDENT WITH THE BOTTOM OF LEAD , WHERE LEAD EXITS BODY

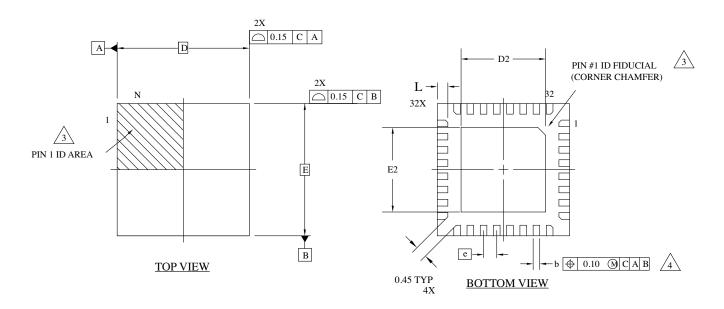
	
- H -	GAGE
	→ eC
	DETAIL A

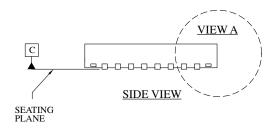
				1
	1			
S Y M	I	NCHES		N
0 L	MIN.	NOM.	MAX.	N O T
Α	-	-	.210	4
A 1	.015	-	-	4
A 2	.115	.130	.195	
b	.014	.018	.022	
b1	.014	.018	.020	
b2	.045	.060	.070	10
С	.008	.010	.014	
c1	.008	.010	.011	
D	1.230	1.250	1.280	5
D1	.005	-	-	5
E	.300	.310	.325	6
E1	.240	.250	.280	5
е	.100 BSC			
eА	.300 BSC			6
eВ	-	-	.430	7
еC	.000	-	.060	7
L	.115	.130	.150	

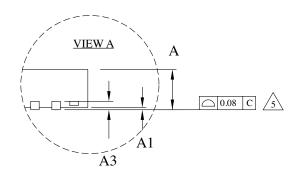


32-Pin QFN Package Option 2: MachXO2[™]

Dimensions in Millimeters







NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

DIMENSION b APPLIES TO PLATED
TERMINAL AND IS MEASURED BETWEEN
0.15 AND 0.30 mm FROM TERMINAL TIP.

APPLIES TO EXPOSED PORTION OF TERMINALS.

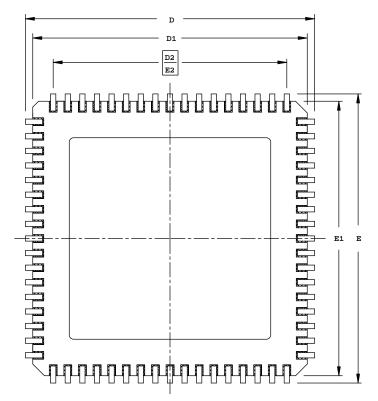
SYMBOL	MIN.	NOM.	MAX.
A	0.50	0.55	0.60
A1	0.00	0.02	0.05
A3	0.2 REF		
D	5.0 BSC		
D2	3.10	3.20	3.30
Е	5.0 BSC		
E2	3.10	3.20	3.30
b	0.20	0.25	0.30
e	0.50 BSC		
L	0.35	0.40	0.45

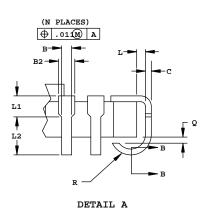


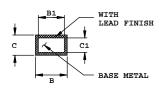
68-Pin JLCC Package

Dimensions in Inches

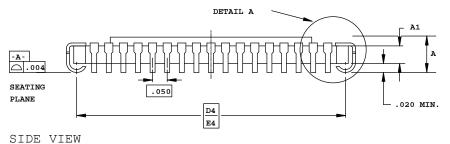
BOTTOM VIEW







SECTION B-B



NOTES:

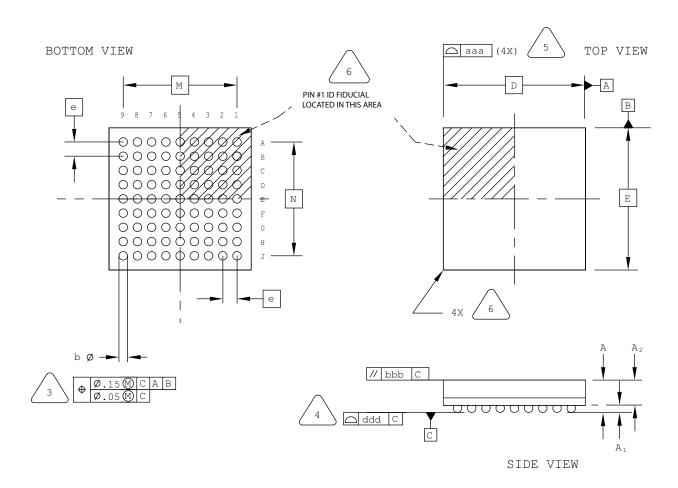
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN INCHES.
- 3. CORNER CHAMFERS AND/OR NOTCHES ARE OPTIONAL.

S M B O L	11	NCHES	
o L	MIN.		MAX.
A	.115	-	.190
A1	. (080 RE	F
В	.013	-	.023
B1	.013	-	.020
B2	.022	-	.035
С	.007	-	.013
C1	.007	-	.010
D/E	.975	.990	1.00
D1/E1	.920	-	.960
D2/E2	. 8	00 BS	С
D4/E4	. 9	30 BS	C
L	.005	-	-
L1	.020	-	-
L2	.025	-	-
Q	.003	-	-
R	.020	-	.040
N		68	



81-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

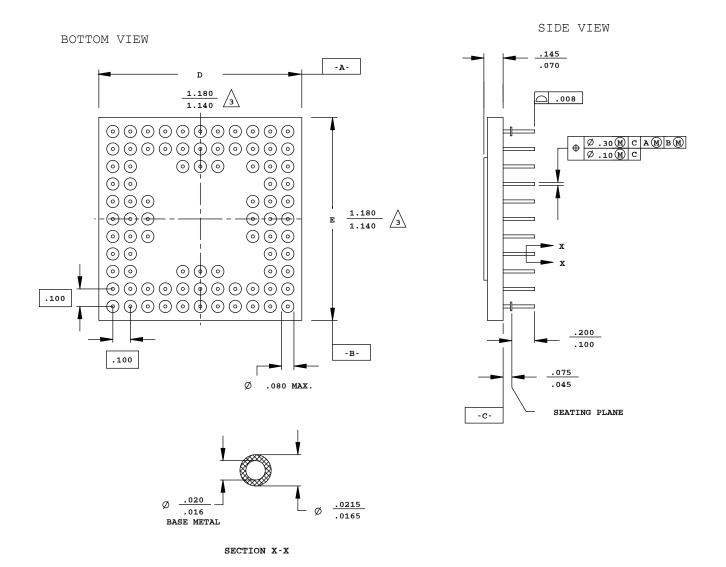


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.00
A1	0.10	_	_
A2	-	_	0.90
D/E	4.00 BSC		
M/N	3.20 BSC		
b	0.20	0.25	0.30
е	0.40 BSC		
aaa	-	_	0.10
bbb	_	_	0.10
ddd	-	_	0.10



84-Pin CPGA Package

Dimensions in Inches



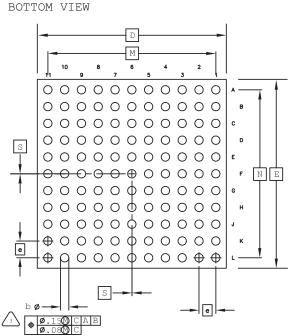
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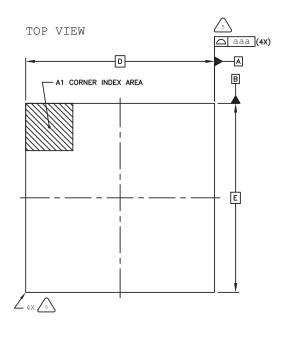
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN INCHES.
- DIMENSIONS D AND E MAY HAVE MATERIAL PROTRUSION OF .006 INCHES MAXIMUM ABOVE THE DIMENSION SHOWN NOT TO EXCEED .003 INCHES MAXIMUM PER SIDE.

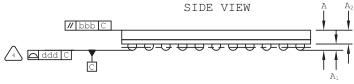


121-Ball caBGA Package (9x9 mm Body)

Dimensions in Millimeters







NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

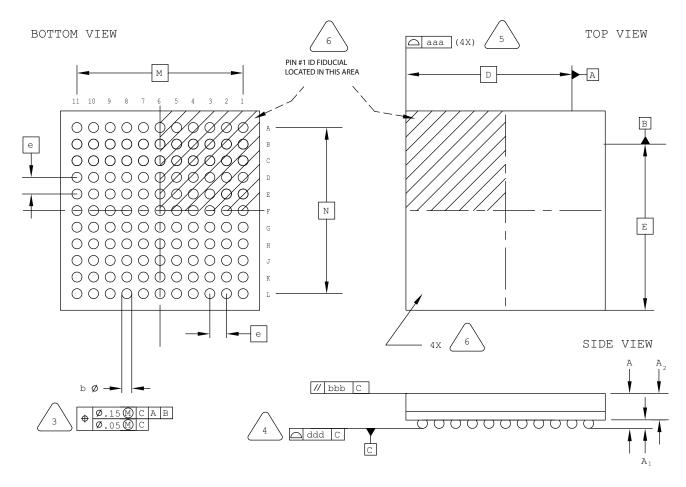


SYMBOL	MIN.	NOM.	MAX.
А	1	ı	1.10
A1	0.15	-	_
A2	0.55	1	ı
D/E	9.00 BSC		
M/N	8.00 BSC		
S	0.00 BSC		
b	0.30	0.40	0.50
е	0.80 BSC		
aaa	0.15		
bbb	0.20		
ddd		0.10	



121-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

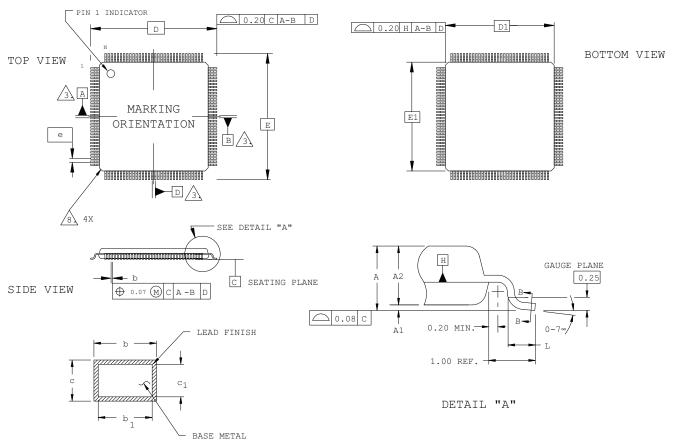


SYMBOL	MIN.	NOM.	MAX.	
А	-	-	1.00	
A1	0.10	_	-	
A2	-	-	0.90	
D/E	6.00 BSC			
M/N	5	5.00 BSC		
b	0.20	0.25	0.30	
е	0.50 BSC			
aaa	_	-	0.10	
bbb	-	-	0.10	
ddd	-	_	0.10	



128-Pin TQFP Package

Dimensions in Millimeters



SECTION B - B

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

A DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION.
 ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

/8\ EXACT SHAPE OF EACH CORNER IS OPTIONAL.

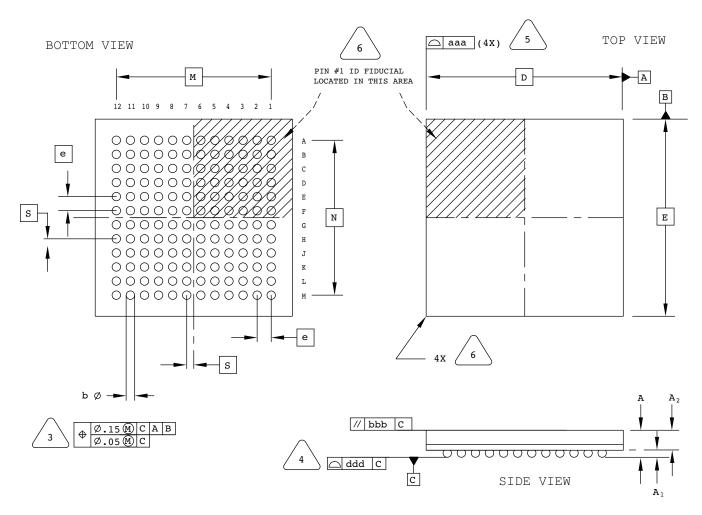
SIDE VIEW

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D		16.00 BSC	
D1		14.00 BSC	
E	16.00 BSC		
E1	14.00 BSC		
L	0.45	0.60	0.75
N	128		
е	0.40 BSC		
b	0.13	0.18	0.23
b1	0.13	0.16	0.19
С	0.09	0.15	0.20
c1	0.09	0.13	0.16



144-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

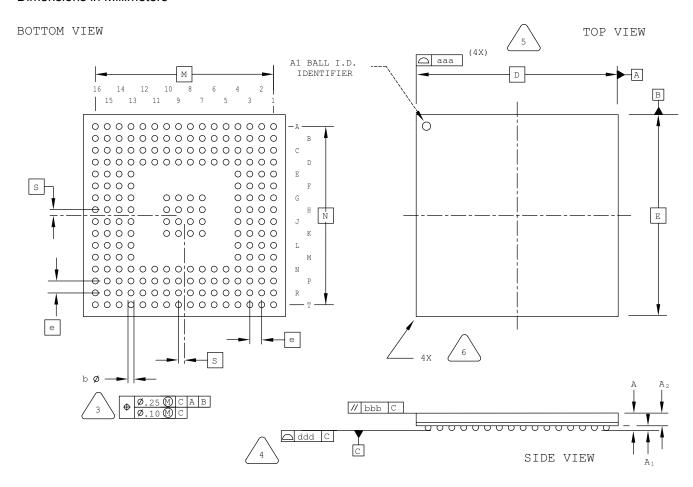


SYMBOL	MIN.	NOM.	MAX.	
A	0.90	1.00	1.10	
A1	0.15	-	-	
A2	_	-	0.85	
D/E	7.00 BSC			
M/N	5.50 BSC			
S	0.25 BSC			
b	0.25	0.30	0.35	
е	0	0.50 BSC		
aaa			0.10	
bbb	-	-	0.10	
ddd	-	-	0.08	



208-Ball ftBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

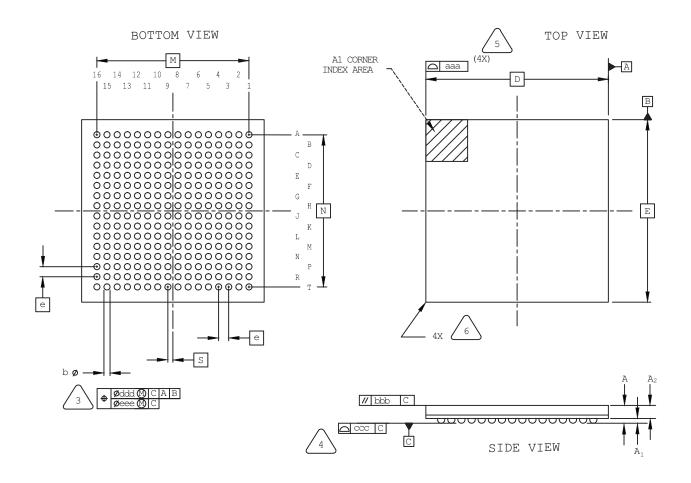


SYMBOL	MIN.	NOM.	MAX.	
А	1.25	1.40	1.55	
A1	0.30	_	_	
A2	-	-	1.25	
D/E	1	17.0 BSC		
M/N	15.0 BSC			
S	0.50 BSC			
b	0.40	0.50	0.60	
е	1.0 BSC			
aaa	-	_	0.20	
bbb	_	_	0.25	
ddd	_	_	0.12	



256-Ball csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\boxed{\mathbb{C}}$.



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

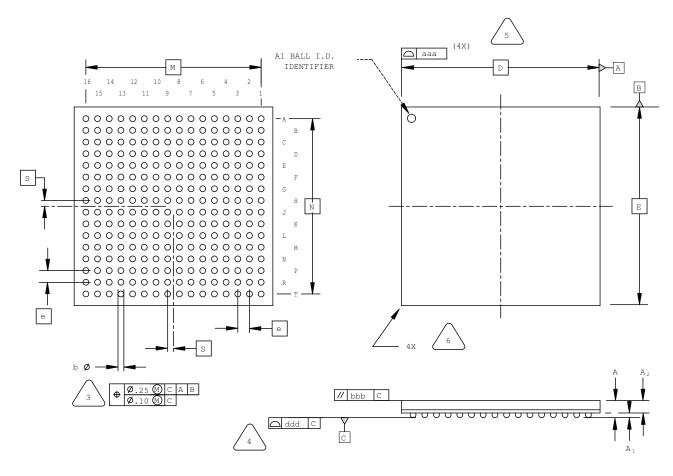


MIN. - 0.15	NOM. - 0.24	MAX. 1.00
- 0.15 -	0.24	1.00
0.15	0.24	
_		_
	0.66	-
	9.00 BSC	
7.50 BSC		
0.25 BSC		
0.25 0.30 0.35		
0.50 BSC		
0.10		
0.10		
0.08		
0.15		
0.05		
		9.00 BSC 7.50 BSC 0.25 BSC 0.25 0.30 0.50 BSC 0.10 0.10 0.10 0.08 0.15



256-Ball ftBGA Package Option 1: ispMACH 4000, MachXO, LatticeXP2

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

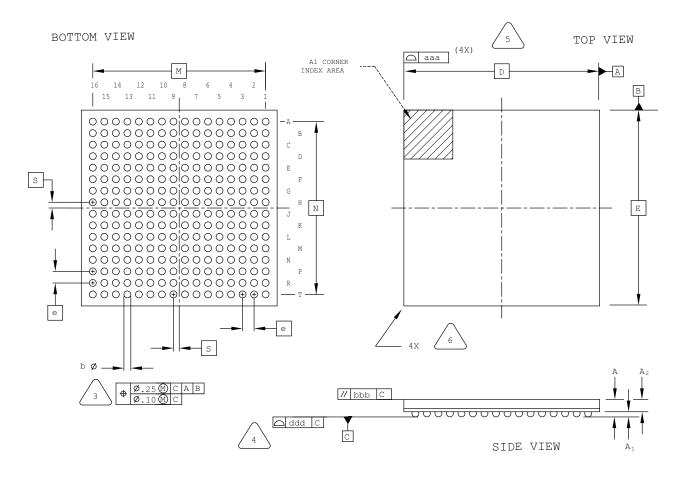


MIN.	NOM.	MAX.
1.25	1.40	1.55
0.30	-	-
_	-	1.25
17.0 BSC		
15.0 BSC		
0.50 BSC		
0.40	0.50	0.60
1.00 BSC		
-	-	0.20
-	-	0.25
		0.12
	1.25 0.30 - 17 15 0.40	1.25 1.40 0.30 17.0 BSC 15.0 BSC 0.50 BSC 0.40 0.50



256-Ball ftBGA Package Option 2: LatticeECP3™

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

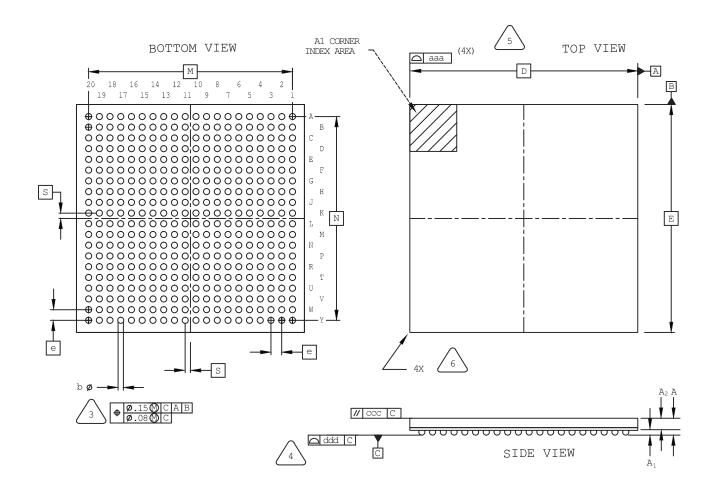


SYMBOL	MIN.	NOM.	MAX.
А	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	1	.40 REF	
D/E	1	17.0 BSC	
M/N	15.0 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.0 BSC		
aaa	_	_	0.20
bbb	-	-	0.25
ddd	_	_	0.20



400-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\boxed{\mathbb{C}}$



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

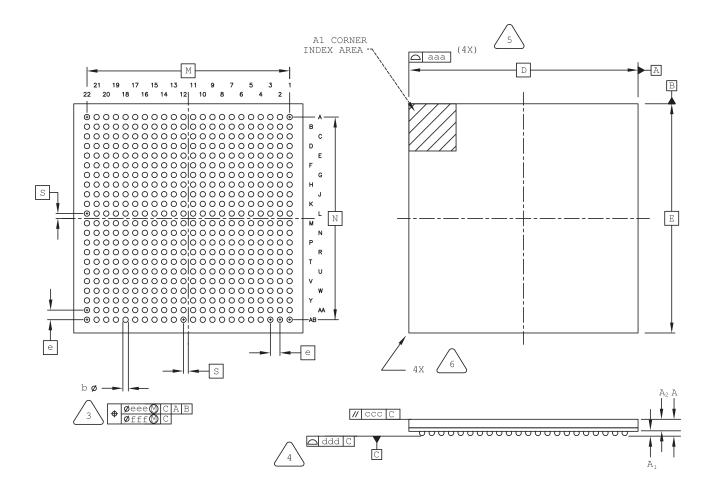


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.70
A1	0.25	0.35	-
A2	0.80	1.00	_
D/E	17.0 BSC		
M/N	15.2 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
е	0.80 BSC		
aaa	_	_	0.15
ccc	_	_	0.20
ddd	_	_	0.20



484-Ball caBGA Package (19x19 mm Body)

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

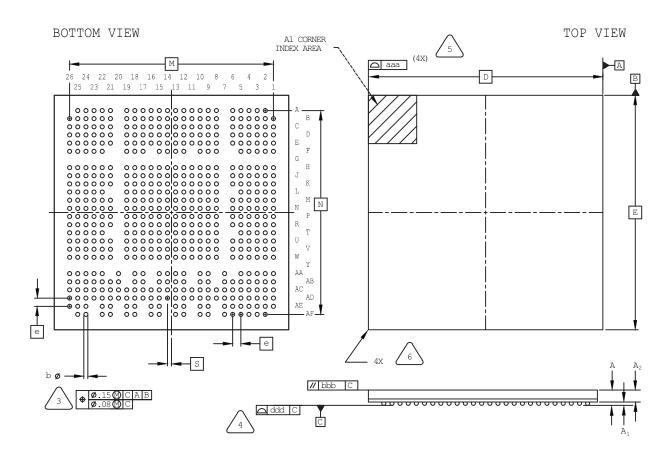
7 JEDEC REFERENCE: MO-275A

SYMBOL	MIN.	NOM.	MAX.
А	-	_	1.70
A1	0.25	-	-
A2	0.65	-	_
D/E	1	9.0 BSC	
M/N	1	6.8 BSC	
S	0.40 BSC		
b	0.40	0.45	0.50
е	0.80 BSC		
aaa	_	-	0.15
ccc	_	_	0.20
ddd	_	-	0.20
eee	_	_	0.15
fff	_	_	0.08



554-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\sqrt{3}$

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

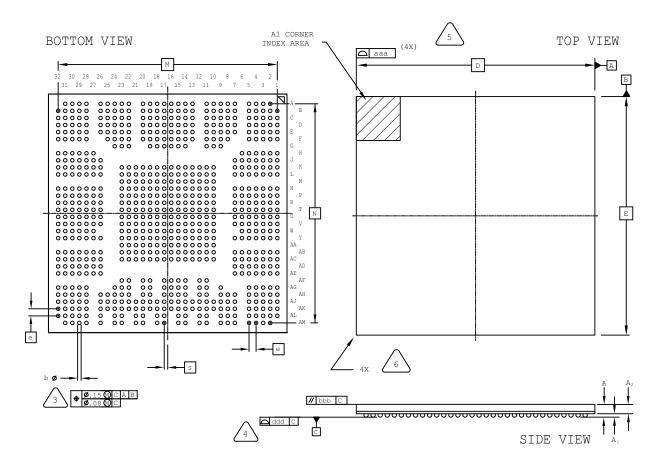


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.76
A1	0.25	0.30	0.35
A2	0.80	ı	ı
D/E	23.0 BSC		
M/N	20.0 BSC		
S	0.40 BSC		
b	0.35	0.40	0.45
е	0.80 BSC		
aaa	_	-	0.15
bbb	_	. 1	0.20
ddd	_		0.12



756-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

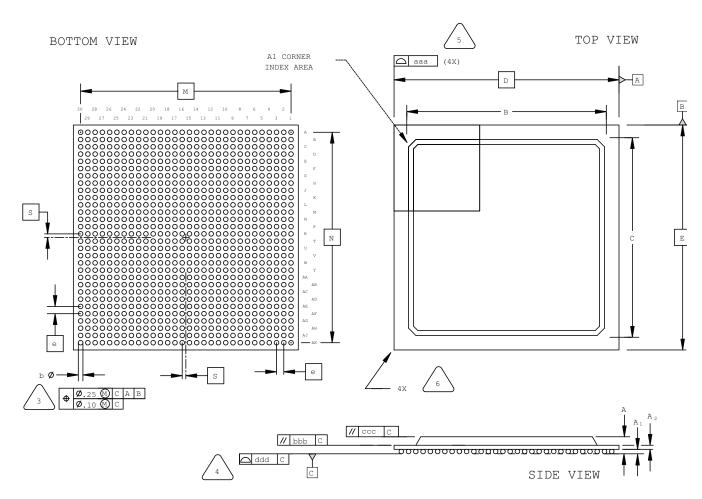


SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.76
A1	0.25	0.30	0.35
A2	0.80	-	-
D/E	27.00 BSC		
M/N	24.80 BSC		
S	0.40 BSC		
b	0.35	0.40	0.45
е	0.80 BSC		
aaa	_	_	0.15
bbb	_	-	0.20
ddd	_	-	0.12



900-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

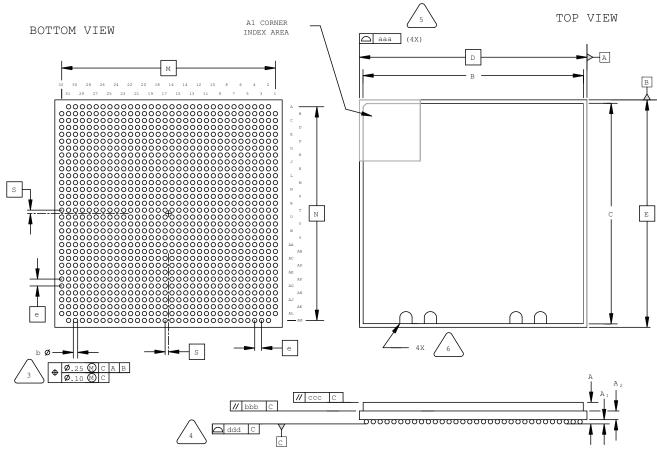


SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	25.80	27.55	29.30
D/E	31.00 BSC		
M/N	29.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20



1020-Ball Organic fcBGA Package

Dimensions in Millimeters



SIDE VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

 DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.
А	2.52	3.12	3.82
A1	0.30	0.50	0.70
A2	1	.24 REF	
B/C	31.10	32.00	32.90
D/E	33.00 BSC		
M/N	31.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	=	0.25
ccc	-	=	0.35
ddd	-	=	0.20